

Alfred Binder

List of Publications by Year in descending order

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Version: 2024-02-01

9
papers

78
citations

1937685
4
h-index

1720034
7
g-index

9
all docs

9
docs citations

9
times ranked

77
citing authors

#	ARTICLE	IF	CITATIONS
1	Exploiting the combination of 3D polymer printing and inkjet Ag-nanoparticle printing for advanced packaging. <i>Microelectronic Engineering</i> , 2017, 176, 1-5.	2.4	28
2	Flip Chip integration of ultra-thinned dies in low-cost flexible printed electronics; the effects of die thickness, encapsulation and conductive adhesives. <i>Microelectronics Reliability</i> , 2021, 123, 114204.	1.7	22
3	Die-Level Thinning for Flip-Chip Integration on Flexible Substrates. <i>Electronics (Switzerland)</i> , 2022, 11, 849.	3.1	8
4	Phase stability comparison of SAW sensor evaluation with various CW type radars. <i>Procedia Engineering</i> , 2010, 5, 661-664.	1.2	7
5	Digital micro-dispension of non-conductive adhesives (NCA) by inkjet printer. , 2017, , .		4
6	Sinterconnects: All-Copper Top-Side Interconnects Based on Copper Sinter Paste for Power Module Packaging. <i>Energies</i> , 2021, 14, 2176.	3.1	4
7	Ultra-Thin Chips (UTC) Integration on Inkjet-Printed Papers. , 2022, , .		3
8	Fast Phase Analysis of SAW Delay Lines. <i>Lecture Notes of the Institute for Computer Sciences, Social-Informatics and Telecommunications Engineering</i> , 2016, , 373-382.	0.3	1
9	Evaluating Cu Printed Interconnects â€œSinterconnectsâ€•versus Wire Bonds for Switching Converters. <i>Electronics (Switzerland)</i> , 2022, 11, 1373.	3.1	1